

MOS INTEGRATED CIRCUIT
 μ PD461016L**1M-BIT BiCMOS FAST STATIC RAM
64K-WORD BY 16-BIT****Description**

The μ PD461016L is 1,048,576 bits (65,536 words by 16 bits), BiCMOS static RAMs. Operating supply voltage is $3.3\text{ V }^{+0.3\text{ V}}_{-0.15\text{ V}}$ or $3.3\text{ V} \pm 0.3\text{ V}$.

The μ PD461016L is packaged in a 44-pin plastic SOJ.

Features

- 65,536 words by 16 bits organization
- Output Enable input for easy application
- Byte data control
- LB: I/O1 to I/O8, $\overline{\text{UB}}$: I/O9 to I/O16
- Fast access time

Ordering Information

Part number	Package	Word organization	Access time ns (MAX.)	Supply Voltage	Supply current mA (MAX.)	
					Operation	Standby
μ PD461016LLE-A10	44-pin plastic SOJ (400 mil)	64K $\times$ 16 bits	10	3.3 V ^{+0.3 V} _{-0.15 V}	260	70
μ PD461016LLE-A11			11	3.3 V $\pm$ 0.3 V		
μ PD461016LLE-A12			12			

Quality grade

Standard

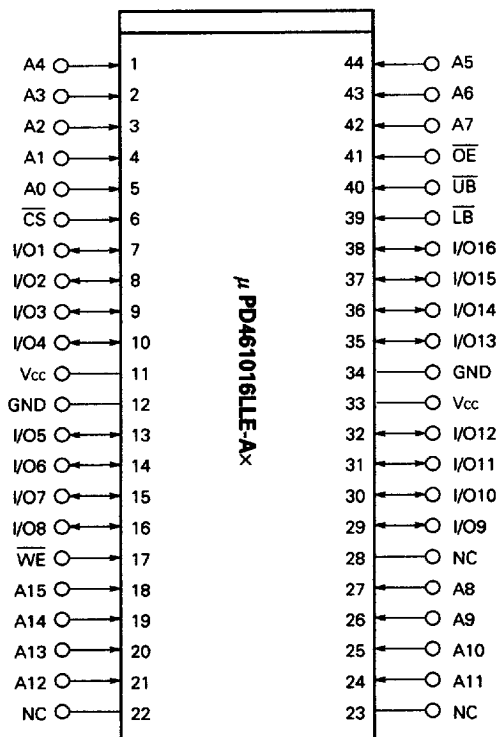
Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

The information in this document is subject to change without notice.

Pin Configuration (Marking Side)

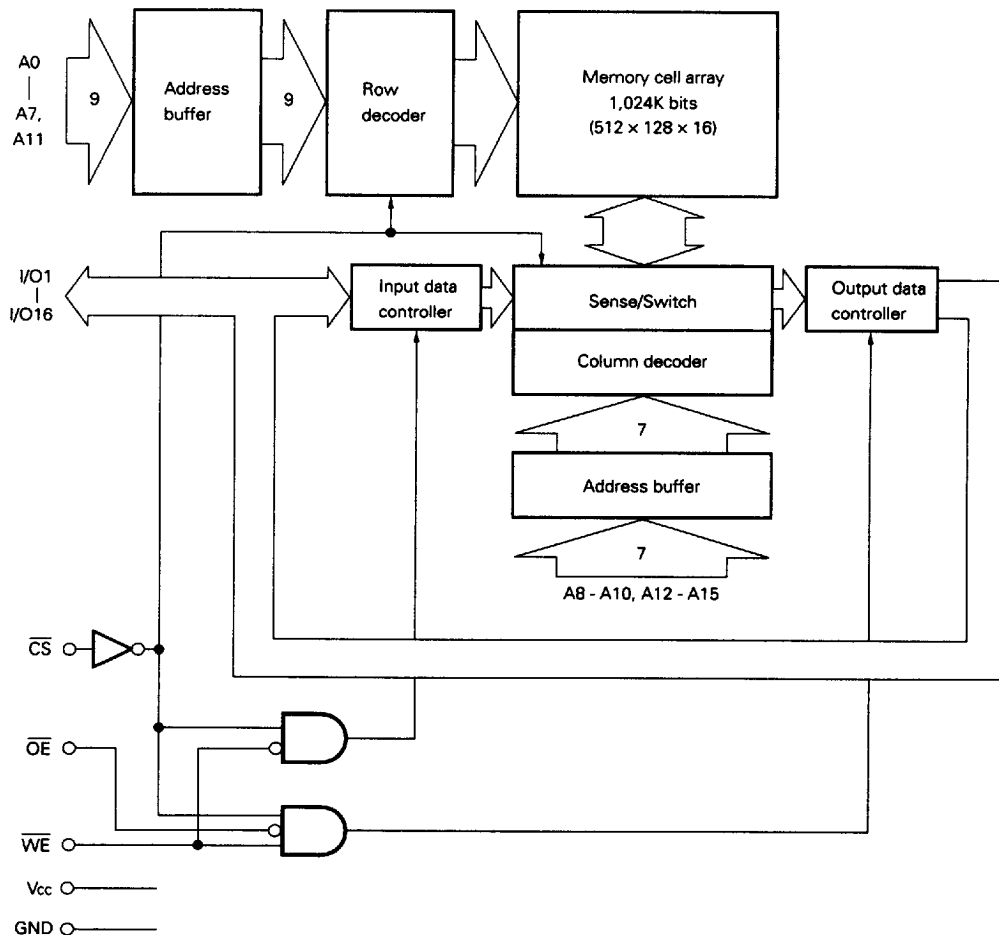
• μPD461016L

44-Pin Plastic SOJ (400 mil)



A0 to A15 : Address Inputs
 I/O1 to I/O16 : Data Inputs/Outputs
 $\overline{CS}$: Chip Select
 $\overline{WE}$: Write Enable
 $\overline{OE}$: Output Enable
 $\overline{LB}$, $\overline{UB}$: Byte data select
 Vcc : Power supply
 GND : Ground
 NC : No Connection

Block Diagram



Truth Table

$\overline{\text{CS}}$	$\overline{\text{OE}}$	$\overline{\text{WE}}$	$\overline{\text{LB}}$	$\overline{\text{UB}}$	Mode	I/O Note		Supply current
						Lower I/O	Upper I/O	
H	x	x	x	x	Not selected	High impedance	High impedance	I _{sa}
L	L	H	L	L	Read	D _{OUT}	D _{OUT}	I _{cc}
			L	H		D _{OUT}	High impedance	
			H	L		High impedance	D _{OUT}	
L	x	L	L	L	Write	D _{IN}	D _{IN}	
			L	H		D _{IN}	High impedance	
			H	L		High impedance	D _{IN}	
L	H	H	x	x	Output disable	High impedance	High impedance	
L	x	x	H	H		High impedance	High impedance	

Note

Part number	Lower I/O	Upper I/O
μPD461016L	I/O1 - I/O8	I/O9 - I/O16

Remark x: Don't care

Electrical Specifications

The device is tested under the minimum transverse air flow of 2.5 meters per second for the DC and AC specifications shown in the following tables.

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage	V _{CC}	-0.5 ^{Note} to +4.6	V
Input voltage	V _{IN}	-0.5 ^{Note} to V _{CC} +0.3	V
Input/Output voltage	V _{I/O}	-0.5 ^{Note} to V _{CC}	V
Operating temperature	T _{opt}	0 to 70	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note -1.0 V (MIN.) (Pulse width: 3 ns)

Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	μ PD461016L-A10			μ PD461016L-A11, 461016L-A12			Unit
		MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Supply voltage	V _{CC}	3.15	3.3	3.6	3.0	3.3	3.6	V
High level input voltage	V _{IH}	2.0		V _{CC} + 0.3	2.0		V _{CC} + 0.3	V
Low level input voltage	V _{IL}	-0.5 ^{Note}		+0.8	-0.5 ^{Note}		+0.8	°C
Ambient temperature	T _a	0		70	0		70	°C

Note -1.0 V (MIN.) (Pulse width: 3 ns)

DC Characteristics (Recommended operating conditions unless otherwise noted)

Parameter	Symbol	Test conditions	MIN.	TYP.	MAX.	Unit
Input leakage current	I_{LI}	$V_{IN} = 0\text{ V to }V_{CC}$	-10		+10	μA
Output leakage current	I_{LO}	$V_{IO} = 0\text{ V to }V_{CC}$, $\overline{CS} = V_{IH}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$ or $\overline{LB} = V_{IH}$ or $\overline{UB} = V_{IH}$	-10		+10	μA
Operating supply current	I_{CC}	$\overline{CS} = V_{IL}$, $I_{VO} = 0\text{ mA}$			260	mA
		Cycle frequency $\leq 100\text{ MHz}$ Cycle frequency = 0 MHz			220	
Standby supply current	I_{SB}	$\overline{CS} = V_{IH}$, $V_{IN} = V_{IH}$ or V_{IL}			100	mA
	I_{SB1}	$\overline{CS} \geq V_{CC} - 0.2\text{ V}$, $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$			70	
High level output voltage	V_{OH}	$I_{OH} = -2.0\text{ mA}$	2.4			V
Low level output voltage	V_{OL}	$I_{OL} = 4\text{ mA}$			0.4	V

Remark V_{IN} : Input voltage**Capacitance ($T_a = 25\text{ }^\circ\text{C}$, $f = 1\text{ MHz}$)**

Parameter	Symbol	Test conditions	MIN.	TYP.	MAX.	Unit
Input capacitance	C_{IN}	$V_{IN} = 0\text{ V}$			6	pF
Input/Output capacitance	C_{IO}	$V_{IO} = 0\text{ V}$			8	pF

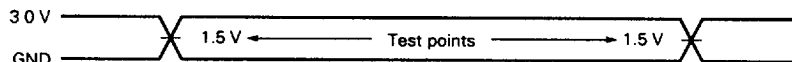
Remark 1. V_{IN} : Input voltage

2. These parameters are periodically sampled and not 100 % tested.

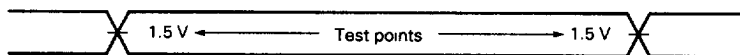
AC Characteristics (Recommended operating conditions unless otherwise noted)

AC Test Conditions

Input waveform (Rise/Fall Time: 2 ns)



Output waveform



Output load

AC characteristics directed with the **Note** should be measured with the following output load shown in **Fig. 1** and **Fig. 2**.

t_{AA} , t_{ACS} , t_{OE} , t_{ABD} and t_{OH} are measured with the output load shown in **Fig. 1**.

t_{CLZ} , t_{OLZ} , t_{BLZ} , t_{CHZ} , t_{OHZ} , t_{BHZ} , t_{WHZ} and t_{OW} are measured with the output load shown in **Fig. 2**.

Fig. 1 Output load
(For t_{AA} , t_{ACS} , t_{OE} , t_{ABD} , t_{OH})

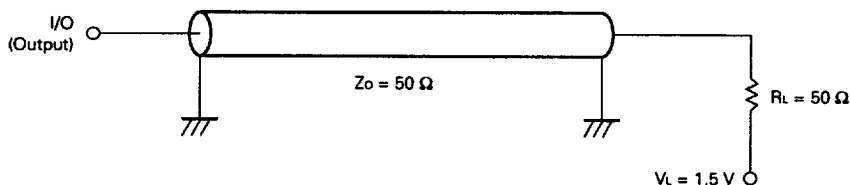
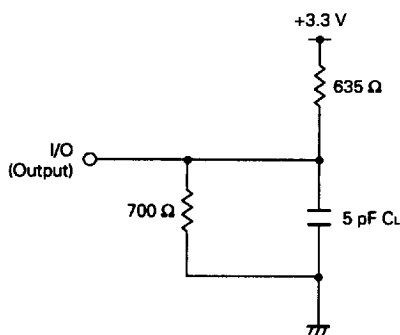


Fig. 2 Output load
(For t_{CLZ} , t_{OLZ} , t_{BLZ} , t_{CHZ} , t_{OHZ} , t_{BHZ} , t_{WHZ} and t_{OW})



Remark C_L includes capacitances of the probe and jig, and stray capacitances.

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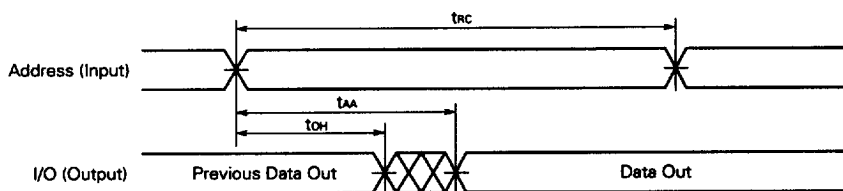
Read Cycle

Parameter	Symbol	μPD461016L-A10		μPD461016L-A11		μPD461016L-A12		Unit	Condition
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read cycle time	trc	10		11		12		ns	
Address access time	tAA		10		11		12	ns	Note 1.
CS access time	tACS		10		11		12	ns	
OE access time	tOE		5		5		6	ns	
LB, UB access time	tABD		5		5		6	ns	
Output hold from address change	tOH	3		3		3		ns	
CS to output in low impedance	tCLZ	3		3		3		ns	Note 2.
OE to output in low impedance	tOLZ	1		1		1		ns	
LB, UB to output in low impedance	tBLZ	1		1		1		ns	
CS to output in high impedance	tCHZ		5		5		6	ns	
OE to output hold in high impedance	tOHZ		5		5		6	ns	
LB, UB to output hold in high impedance	tBHZ		5		5		6	ns	

Note 1. See the output load shown in Fig. 1.

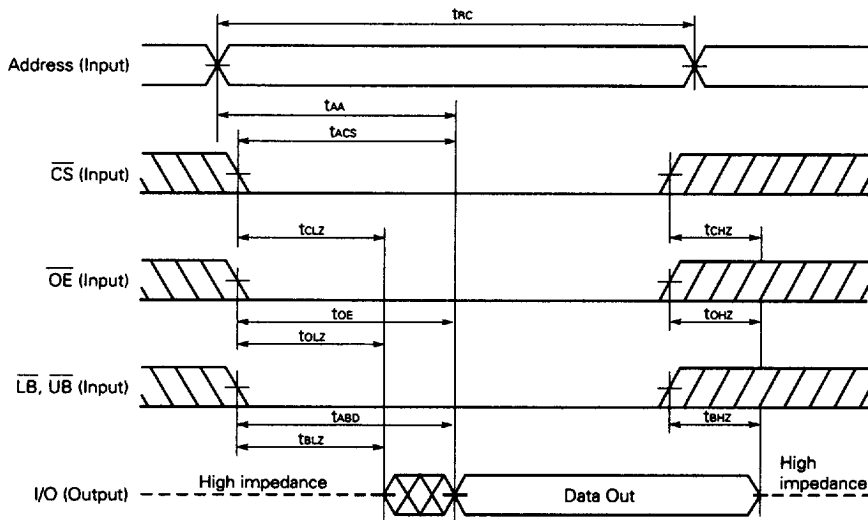
2. See the output load shown in Fig. 2.

Read Cycle Timing Chart 1 (Address Access)



Remark 1. In read cycle, $\overline{WE}$ should be fixed to high level.

2. $\overline{CS} = \overline{OE} = \overline{LB}$ (or $\overline{UB}$) = V_{IL}

Read Cycle Timing Chart 2 ($\overline{\text{CS}}$ Access)

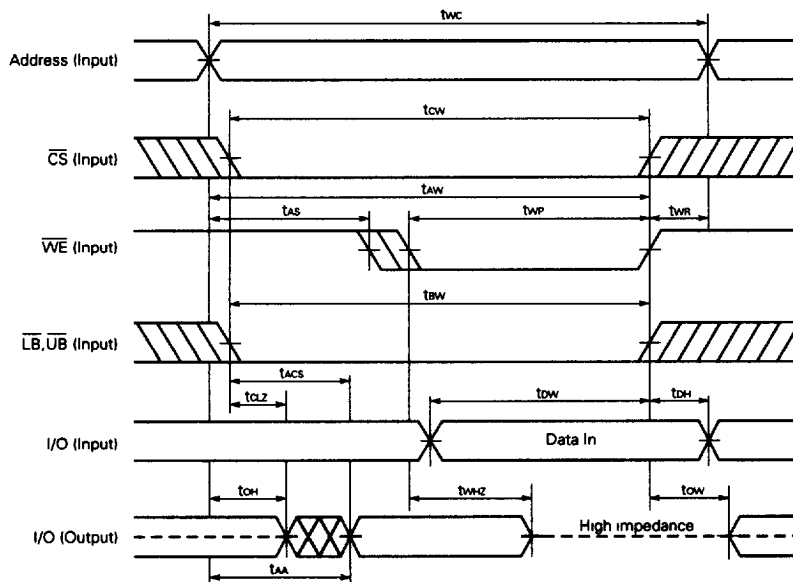
Caution Address valid prior to or coincident with $\overline{\text{CS}}$ low level input.

Remark In read cycle, $\overline{\text{WE}}$ should be fixed to high level.

Write Cycle

Parameter	Symbol	μPD461016L-A10		μPD461016L-A11		μPD461016L-A12		Unit	Condition
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Write cycle time	t _{WC}	10		11		12		ns	
CS to end of write	t _{OW}	8		9		10		ns	
Address valid to end of write	t _{AW}	8		9		10		ns	
Write pulse width	t _{WP}	8		9		10		ns	
LB, UB to end of write	t _{EW}	8		9		10		ns	
Data valid to end of write	t _{OW}	6		7		8		ns	
Data hold time	t _{DH}	0		0		0		ns	
Address setup time	t _{AS}	0		0		0		ns	
Write recovery time	t _{WR}	0		0		0		ns	
WE to output in high impedance	t _{WHZ}		5		5		6	ns	Note
Output active from end of write	t _{OW}	3		3		3		ns	

Note See the output load shown in Fig. 2.

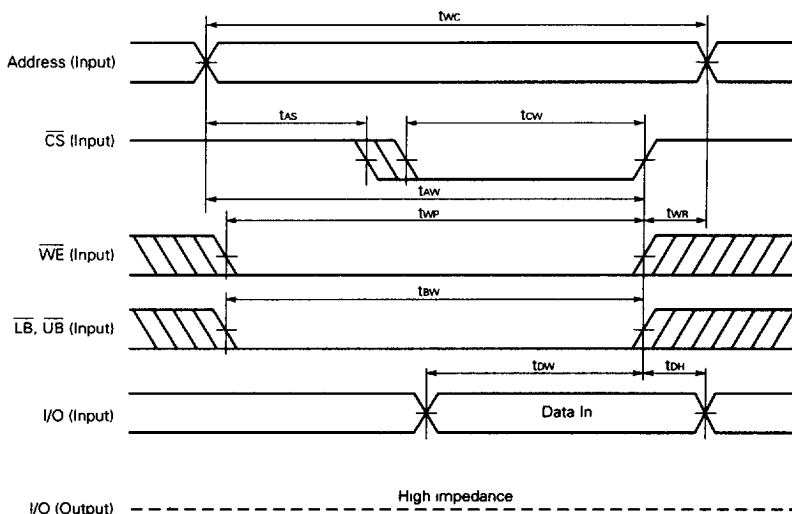
Write Cycle Timing Chart 1 ($\overline{WE}$ Controlled)

Caution $\overline{CS}$ or $\overline{WE}$ should be fixed to high level during address transition.

Remark 1. Write operation is done during the overlap time of low level $\overline{CS}$, low level $\overline{WE}$ and low level $\overline{LB}$ (or low level $\overline{UB}$).

2. During t_{whz} , I/O pins are in the output state, therefore the input signals of opposite phase to the output must not be applied.
3. When $\overline{WE}$ is at low level, the I/O pins are always high impedance. When $\overline{WE}$ is at high level, read operation is executed. Therefore $\overline{OE}$ should be at high level to make the I/O pins high impedance.

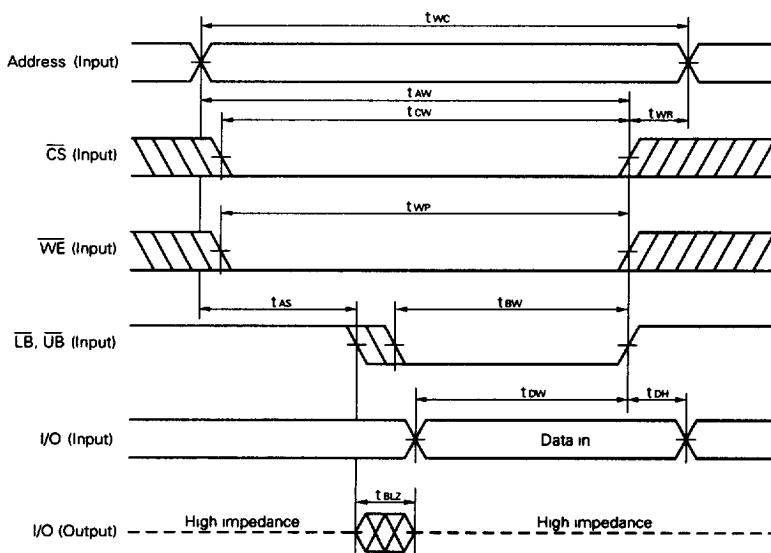
Write Cycle Timing Chart 2 (CS Controlled)



Caution CS or WE should be fixed to high level during address transition.

Remark Write operation is done during the overlap time of a low level CS, low level WE and low level LB (or low level UB).

Write Cycle Timing Chart 3 (LB, UB Controlled)



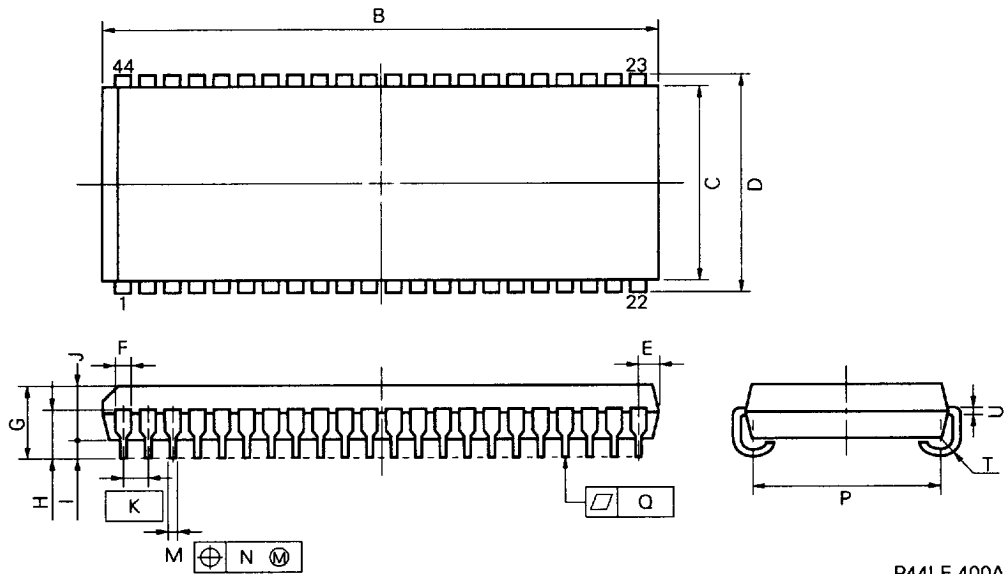
Caution CS or WE should be fixed to high level during address transition.

Remark Write operation is done during the overlap time of a low level CS, low level WE and low level LB (or low level UB).

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Package Drawings

44 PIN PLASTIC SOJ (400 mil)



NOTE
Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

P44LE-400A

ITEM	MILLIMETERS	INCHES
B	28.73 ^{+0.2} _{-0.35}	1.131 ^{+0.008} _{-0.014}
C	10.16	0.400
D	11.18±0.20	0.440±0.008
E	1.03±0.15	0.041 ^{+0.006} _{-0.007}
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.3±0.2	0.091 ^{+0.008} _{-0.009}
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	0.016 ^{+0.004} _{-0.005}
N	0.12	0.005
P	9.4±0.20	0.370±0.008
Q	0.10	0.004
T	R 0.85	R 0.033
U	0.20 ^{+0.10} _{-0.05}	0.008 ^{+0.004} _{-0.002}

Recommended Soldering Conditions

Please consult with our sales offices for soldering conditions of the μ PD461016L.

Types of Surface Mount Device

μ PD461016LLE : 44-pin plastic SOJ (400 mil)